

描述 / Descriptions

SOP-8 塑封封装双 P 沟道 MOS 场效应管。Dual P-Channel MOSFET in a SOP-8 Plastic Package.

特征 / Features

超高密度设计，导通电阻小，可靠性好。无卤产品。

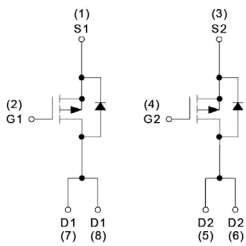
Super high dense cell design for low $R_{DS(ON)}$, Rugged and reliable. HF Product.

用途 / Applications

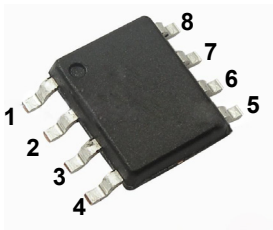
用于电源管理，便携式设备和电池供电系统。

Power Management in Notebook computer, Portable Equipment and Battery powered systems.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN 1 : S1 PIN 2 : G1 PIN 3 : S2 PIN 4 : G2

PIN 5 : D2 PIN 6 : D2 PIN 7 : D1 PIN 8 : D1

印章代码 / Marking

Marking	4953D
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极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V_{GSS}	±12	V
Continuous Drain Current	I_D^*	-3.0	A
Pulsed Drain Current	I_{DM}^*	-12	A
Diode Continuous Forward Current	I_S^*	-2.0	A
Power Dissipation for Single Operation	$P_D^*(Ta=25^\circ C)$	2	W
Power Dissipation for Single Operation	$P_D^*(Ta=100^\circ C)$	0.8	W
Maximum Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55 ~ 150	°C
Thermal Resistance-Junction to Ambient	$R_{\theta JA}^*$	62.5	°C/W

Note:

* Surface Mounted on 1in2 pad area, $t \leq 10$ sec.

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V$ $I_{DS}=-250\mu A$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-16V$ $V_{GS}=0V$			-1	μA
		$V_{DS}=-16V$ $V_{GS}=0V$ $T_j=85^\circ C$			-10	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_{DS}=-250\mu A$	-0.50	-0.8	-1.0	V
Gate Leakage Current	I_{GSS}	$V_{GS}=\pm 12V$ $V_{DS}=0V$			±100	nA
Drain-Source On-state Resistance	$R_{DS(ON)}^a$	$V_{GS}=-10V$ $I_{DS}=-2.7A$		85	97	mΩ
		$V_{GS}=-4.5V$ $I_{DS}=-2.7A$		82	110	
		$V_{GS}=-2.5V$ $I_{DS}=-2.2A$		130	150	
Diode Forward Voltage	V_{SD}^a	$V_{GS}=0V$ $I_{SD}=-1.0A$		-0.7	-1.3	V
Total Gate Charge	Q_g^b	$V_{DS}=-6V$ $V_{GS}=-4.5V$ $I_{DS}=-2.7A$		5.8	10	nC
Gate-Source Charge	Q_{gs}^b			0.85		nC
Gate-Drain Charge	Q_{gd}^b			1.7		nC

电性能参数 / Electrical Characteristics(Ta=25°C)

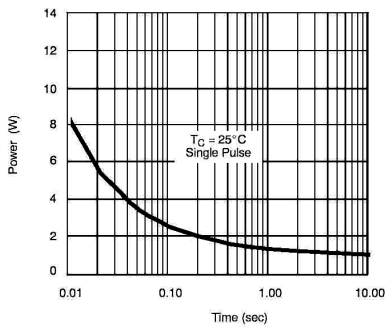
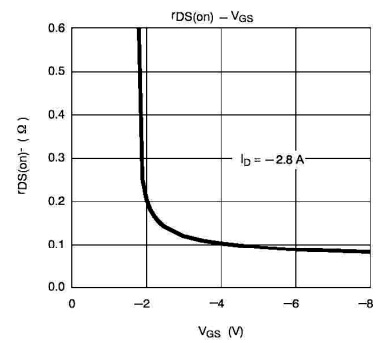
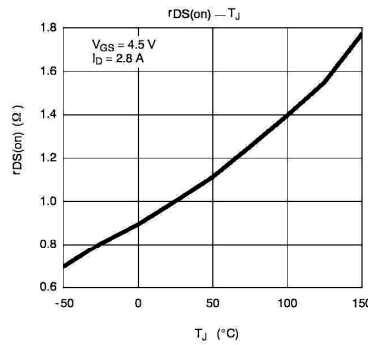
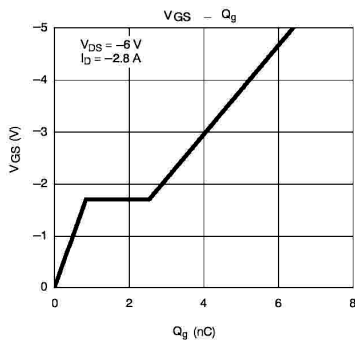
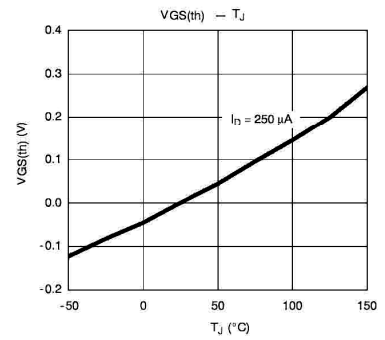
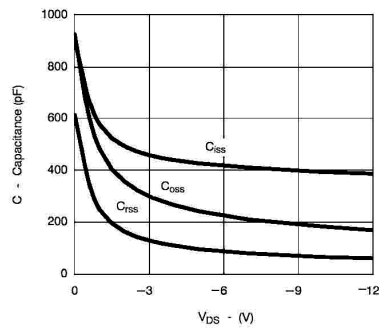
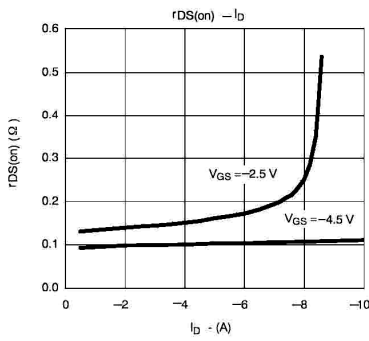
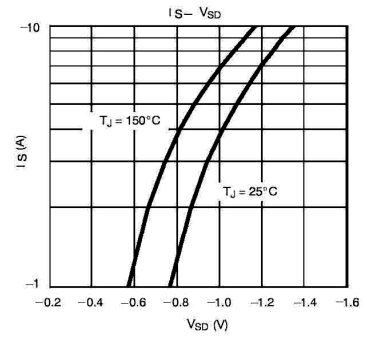
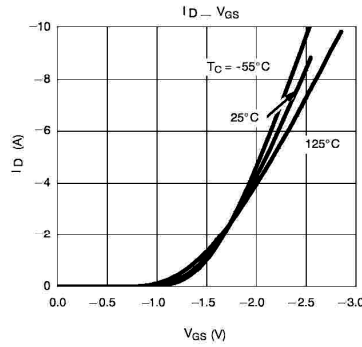
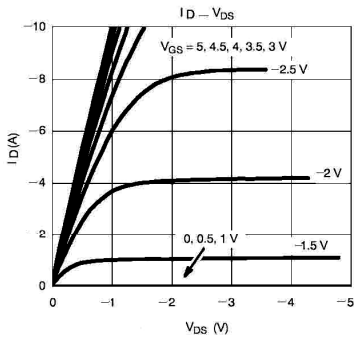
参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Gate Resistance	R_G^b	$V_{GS}=0V$ $V_{DS}=0V$ $F=1MHz$		6		Ω
Input Capacitance	C_{iss}^b	$V_{GS}=0V$ $V_{DS}=-6V$ Frequency=1.0MHz		415		pF
Output Capacitance	C_{oss}^b			223		
Reverse Transfer Capacitance	C_{rss}^b			84		
Turn-on Delay Time	$t_{d(ON)}^b$	$V_{DD}=-6V$ $R_L=6\Omega$ $I_{DS}=-1A$ $V_{GEN}=-10V$ $R_G=6\Omega$		13	25	ns
Turn-on Rise Time	T_r^b			36	60	
Turn-off Delay Time	$T_{d(OFF)}^b$			42	70	
Turn-off Fall Time	T_f^b			34	60	

Notes:

a : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

b : Guaranteed by design, not subject to production testing.

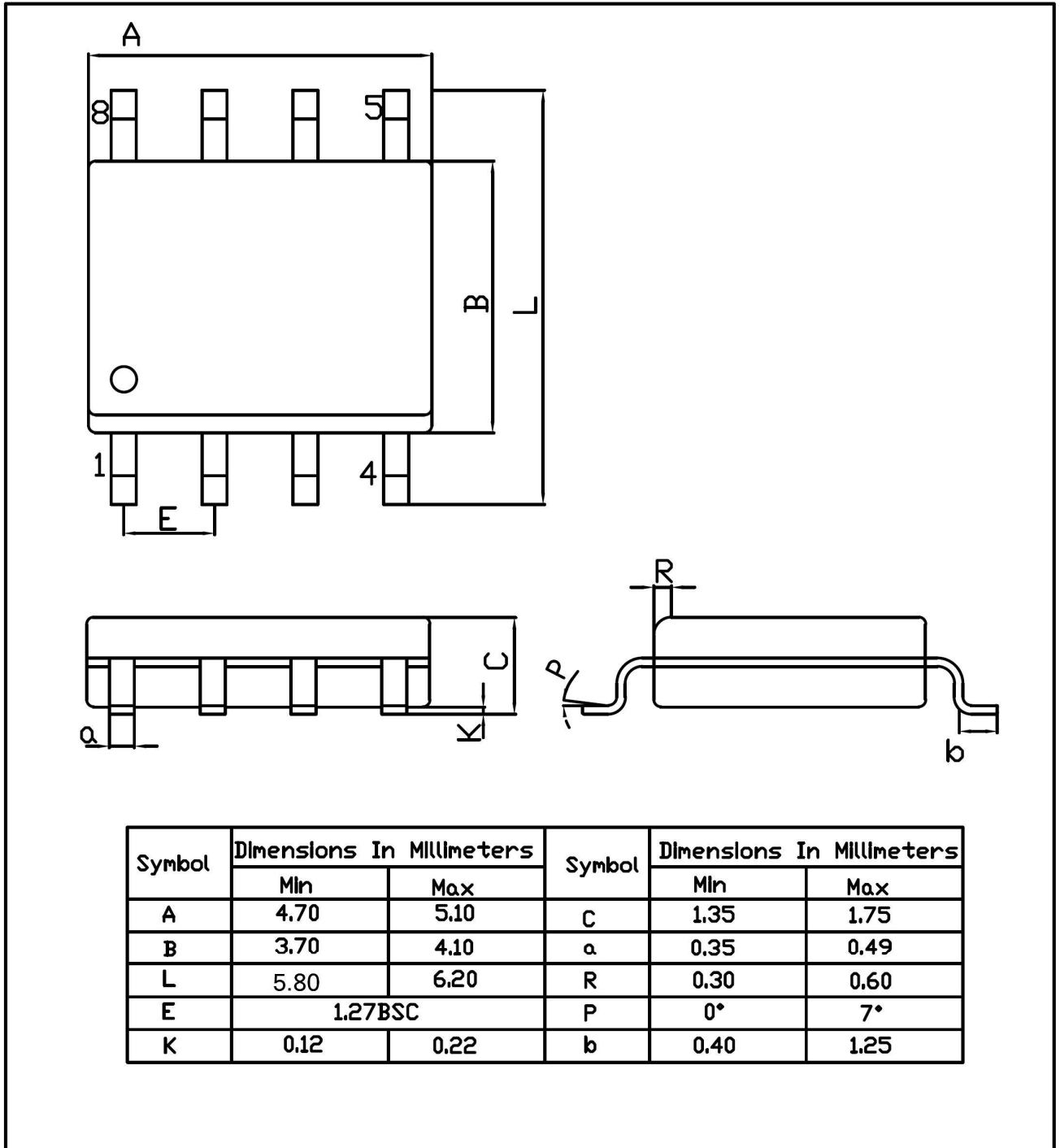
电参数曲线图 / Electrical Characteristic Curve



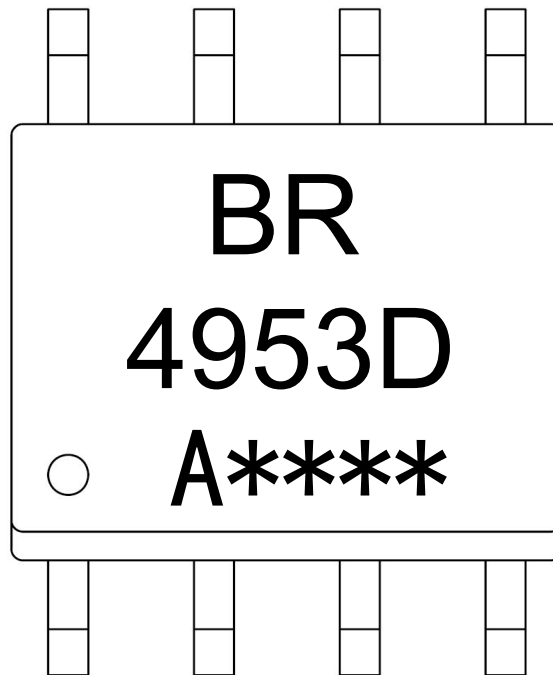
外形尺寸图 / Package Dimensions

SOP-8

Unit:mm



印章说明 / Marking Instructions



说明：

BR： 为公司代码

4953D： 为型号代码

A： 为芯片标识位（标识位可空,也可为 A、B、C、D.....等字母）

****： 为生产批号代码，随生产批号变化。

Note:

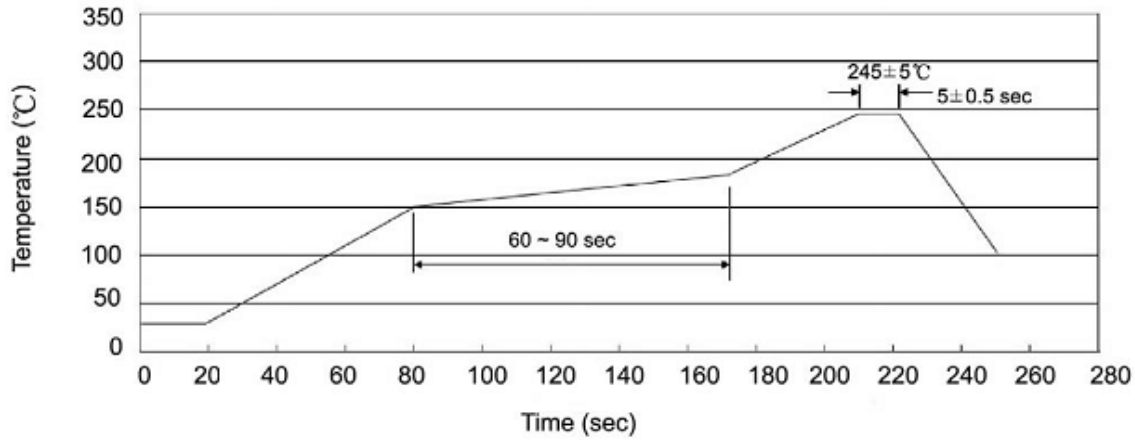
BR: Company Code.

4953D: Product Type

A: Chip sign(Flag bit may be empty,or the letter A、B、C、D.....).

****: Lot No. Code, code change with Lot No.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOP/ESOP-8	4,000	2	8,000	6	48,000	13" ×12	360×360×50	380×335×366

使用说明 / Notices

不同芯片标识的产品可以替换使用，为确保一致性，建议同一批次使用相同芯片标识的产品。

Different chip sign products can be used to replace ,in order to ensure consistency .We suggest to use the same chip sign products for the same batch.